

2827

MEG01-004

Serial number 09/837,007

TO: COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

From : George O. Saile (Reg. No. 19,572)  
28 Davis Avenue  
Poughkeepsie, NY 12603

Date: February 15, 2003

REF: APPLICANT : Mou-Shiung Lin  
SERIAL NO. : 09/837,007  
ART UNIT : 2827  
FILING DATE : 04/18/01  
ATT'Y NO. : MEG01-004  
EXAMINER : Mitchell, James M.  
TITLE : A STRUCTURE AND MANUFACTURING  
METHOD OF A CHIP SCALE PACKAGE

AMENDMENT AND RESPONSE TO OFFICE ACTION

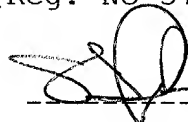
Sir:

In response to an office action mailed on 11/19/02  
please consider the following amendments and remarks with  
respect to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal service as First  
Class mail in an envelop addressed to the Commissioner of  
Patents and Trademarks, Washington, D.C. 20231, on  
February 19, 2003.

Stephen B. Ackerman (Reg. No 37,761)

  
Signature

2/19/03  
Date

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